

# VECTRA® FIT30

## Liquid Crystal Polymer

43% glass and mineral reinforced grade. Glass and mineral filled grade, high flow and low warpage.

Chemical abbreviation according to ISO 1043-1 : LCP Inherently flame retardant

### Product information

|                      |                 |           |
|----------------------|-----------------|-----------|
| Resin Identification | LCP-(GF+MD)4    | ISO 1043  |
|                      | 3               |           |
| Part Marking Code    | >LCP-(GF+MD)43< | ISO 11469 |

### Typical mechanical properties

|                                      |                        |              |
|--------------------------------------|------------------------|--------------|
| Tensile modulus                      | 13000 MPa              | ISO 527-1/-2 |
| Tensile stress at break, 5mm/min     | 110 MPa                | ISO 527-1/-2 |
| Tensile strain at break, 5mm/min     | 1.3 %                  | ISO 527-1/-2 |
| Flexural modulus                     | 13000 MPa              | ISO 178      |
| Flexural strength                    | 160 MPa                | ISO 178      |
| Flexural strain at failure           | 1.9 %                  | ISO 178      |
| Charpy impact strength, 23°C         | 25.5 kJ/m <sup>2</sup> | ISO 179/1eU  |
| Charpy notched impact strength, 23°C | 6 kJ/m <sup>2</sup>    | ISO 179/1eA  |
| Poisson's ratio                      | 0.33 <sup>[C]</sup>    |              |

[C]: Calculated

### Thermal properties

|                                                          |                          |                |
|----------------------------------------------------------|--------------------------|----------------|
| Melting temperature, 10°C/min                            | 328 °C                   | ISO 11357-1/-3 |
| Temperature of deflection under load, 1.8 MPa            | 262 °C                   | ISO 75-1/-2    |
| Temperature of deflection under load, 0.45 MPa           | 286 °C                   | ISO 75-1/-2    |
| Ball pressure test                                       | 250 °C                   | IEC 60695-10-2 |
| Coefficient of linear thermal expansion (CLTE), parallel | 9 E-6/K                  | ISO 11359-1/-2 |
| Coefficient of linear thermal expansion (CLTE), normal   | 38 E-6/K                 | ISO 11359-1/-2 |
| Thermal conductivity, through plane                      | 0.26 W/(m K)             | ISO 22007-2    |
| Effective thermal diffusivity, through plane             | 1.8E-7 m <sup>2</sup> /s | ISO 22007-4    |
| Specific heat capacity of melt                           | 810 J/(kg K)             | ISO 22007-4    |

### Electrical properties

|                                                             |                             |                 |
|-------------------------------------------------------------|-----------------------------|-----------------|
| Dissipation factor, 1GHz                                    | 63 E-4                      | IEC 61189-2-721 |
| Volume resistivity                                          | 1E14 <sup>[OT]</sup> Ohm.m  | IEC 62631-3-1   |
| Volume resistivity, at high temperature                     | 1E10 <sup>[OT]</sup> Ohm.m  | IEC 62631-3-1   |
| Temperature                                                 | 220 <sup>[OT]</sup> °C      |                 |
| Surface resistivity                                         | 1E16 <sup>[OT, 1]</sup> Ohm | IEC 62631-3-2   |
| Surface resistivity, at high temperature                    | 1E13 <sup>[OT]</sup> Ohm    | IEC 62631-3-2   |
| Temperature                                                 | 220 <sup>[OT]</sup> °C      |                 |
| Electric strength                                           | 37 kV/mm                    | IEC 60243-1     |
| Electric strength, Direct Current                           | 40 <sup>[OT]</sup> kV/mm    | IEC 60243-2     |
| Electric strength, DC, high temperature                     | 28 <sup>[OT]</sup> kV/mm    | IEC 60243-2     |
| Temperature                                                 | 220 <sup>[OT]</sup> °C      |                 |
| Relative permittivity, printed circuits and boards, 2.5 GHz | 4.4                         | IEC 61189-2-721 |

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## Liquid Crystal Polymer

Dissipation factor, printed circuits and boards, 2.5 GHz

53 E-4

IEC 61189-2-721

[OT]: One time tested

[1]: historical value

## Physical/Other properties

Humidity absorption, 2mm

0.02 %

Sim. to ISO 62

Density

1770 kg/m<sup>3</sup>

ISO 1183

## Injection

Drying Recommended

yes

Drying Temperature

150 °C

Drying Time, Dehumidified Dryer

4 - 6 h

Processing Moisture Content

≤0.01 %

Melt Temperature Optimum

340 °C

Min. melt temperature

335 °C

Max. melt temperature

345 °C

Screw tangential speed

0.2 - 0.3 m/s

Mold Temperature Optimum

100 °C

Min. mould temperature

80 °C

Max. mould temperature

130 °C

Ejection temperature

240 °C

## Characteristics

Processing

Injection Moulding, Extrusion

Special characteristics

Flame retardant, Heat stabilised or stable to heat, High Flow, Low Warpage

## Additional information

Processing Notes

### Pre-Drying

VECTRA should in principle be predried. Because of the necessary low maximum residual moisture content the use of dry air dryers is recommended. The dew point should be ≤ - 40° C. The time between drying and processing should be as short as possible.

### Storage

For subsequent storage of the material in the dryer until processed the temperature does not need to be lowered for grades A, B, C, D and V (≤ 24 h).